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April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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BB501C

Built in Biasing Circuit MOS FET IC UHF RF Amplifier

REJ03G0830-0600 (Previous ADE-208-701D) Rev.6.00 Aug.10.2005

Features

- Built in Biasing Circuit; To reduce using parts cost & PC board space.
- High gain;

PG = 21.5 dB typ. at f = 900 MHz

• Low noise;

NF = 1.85 dB typ. at f = 900 MHz

Withstanding to ESD;

Built in ESD absorbing diode. Withstand up to 200V at C=200pF, Rs=0 conditions.

• Provide mini mold packages; CMPAK-4(SOT-343mod)

Outline

RENESAS Package code: PTSP0004ZA-A

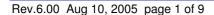
(Package name: CMPAK-4)



- 1. Source
- 2. Gate1
- 3. Gate2
- 4. Drain

Notes: 1. Marking is "AS -".

BB501C is individual type number of RENESAS BBFET.



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

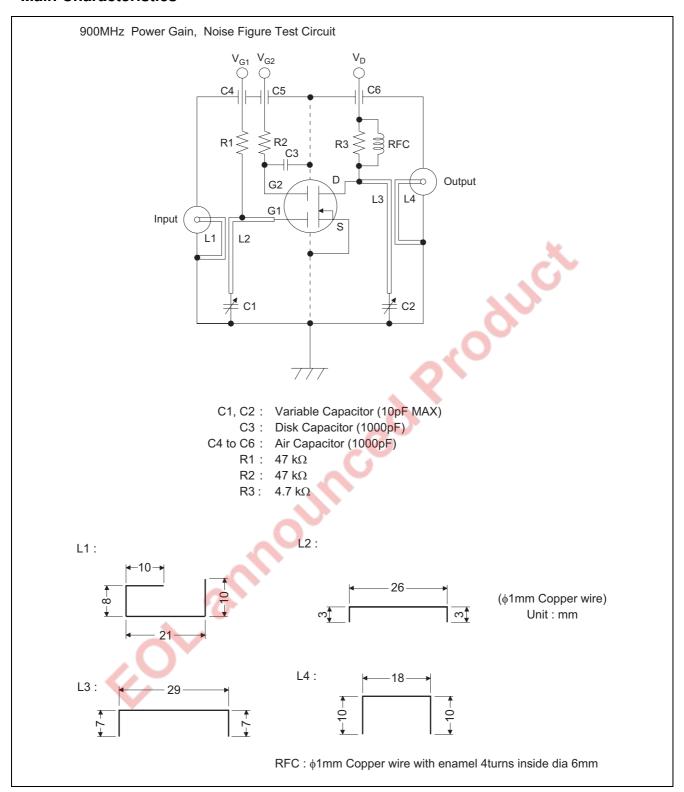
Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DS}	6	V
Gate1 to source voltage	V_{G1S}	+6	V
		- 0	
Gate2 to source voltage	V_{G2S}	+6	V
		- 0	
Drain current	I _D	20	mA
Channel power dissipation	Pch	100	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

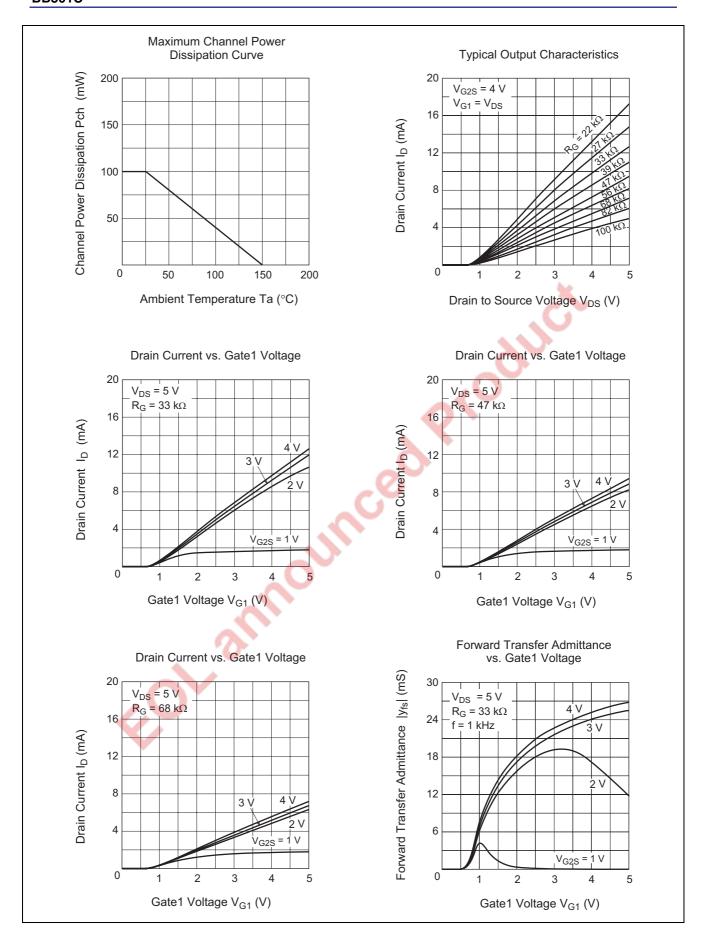
Electrical Characteristics

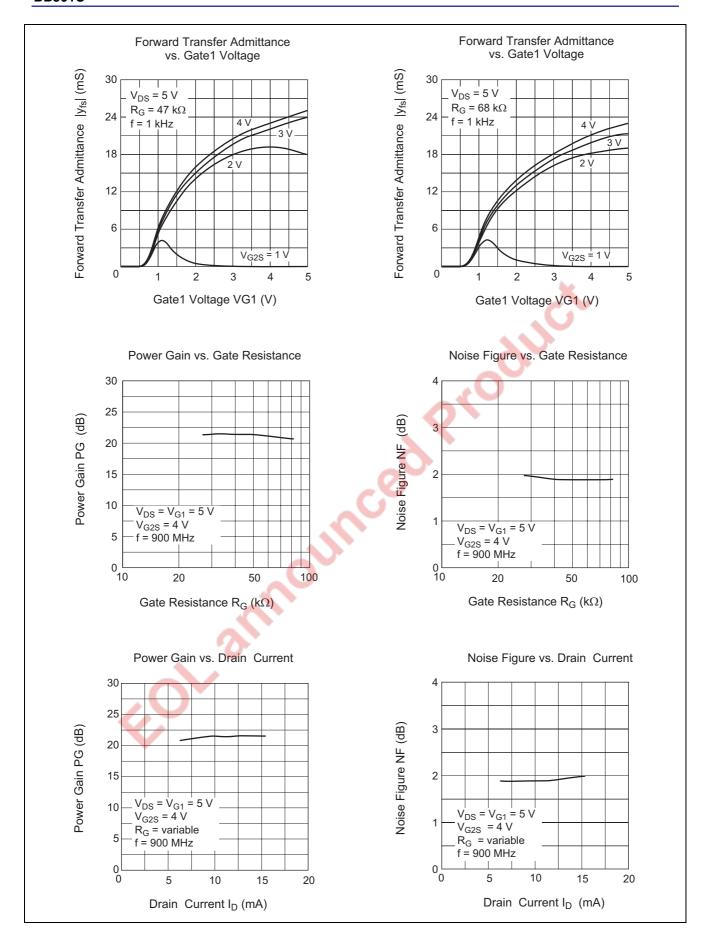
 $(Ta = 25^{\circ}C)$

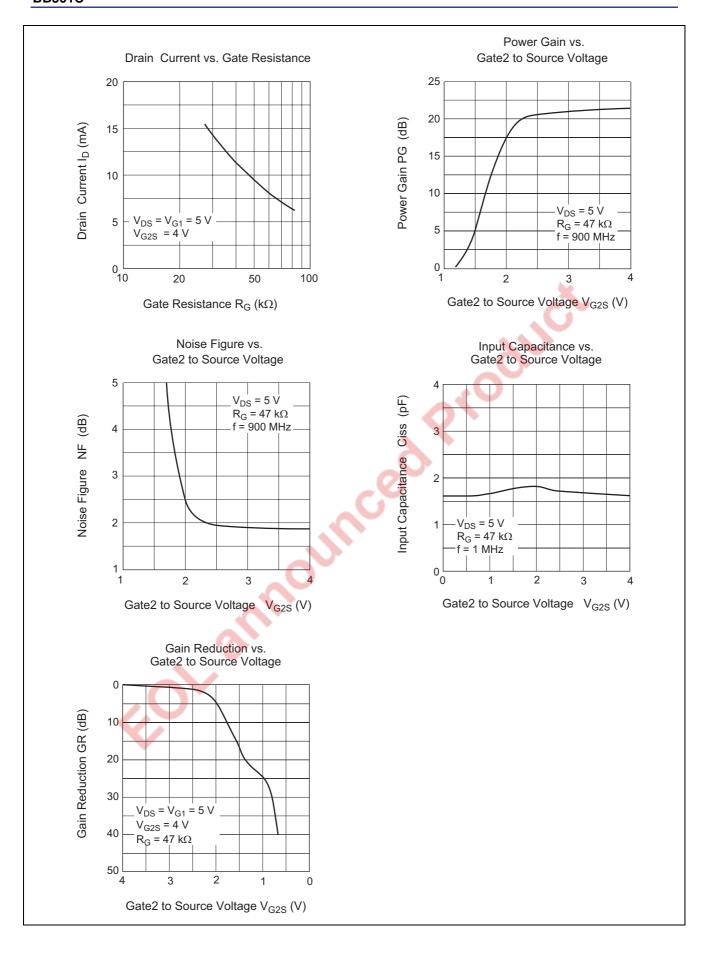
Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	6	_	_	V	$I_D = 200 \mu\text{A}, V_{\text{G1S}} = V_{\text{G2S}} = 0$	
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	+6	_	_	V	$I_{G1} = +10 \mu A, V_{G2S} = V_{DS} = 0$	
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	+6	_	_	V	$I_{G2} = +10 \mu A, V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff current	I _{G1SS}	_	_	+100	nA	$V_{G1S} = +5 \text{ V}, V_{G2S} = V_{DS} = 0$	
Gate2 to source cutoff current	I _{G2SS}	_	_	+100	nA	$V_{G2S} = +5 \text{ V}, V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff voltage	V _{G1S(off)}	0.5	0.7	1.0	V	V _{DS} = 5 V, V _{G2S} = 4 V	
						$I_D = 100 \mu A$	
Gate2 to source cutoff voltage	$V_{G2S(off)}$	0.5	0.7	1.0	V	$V_{DS} = 5 \text{ V}, V_{G1S} = 5 \text{ V}$	
						$I_D = 100 \mu A$	
Drain current	$I_{D(op)}$	7	10	13	mA	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$	
						$V_{G2S} = 4 \text{ V}, R_G = 47 \text{ k}\Omega$	
Forward transfer admittance	y _{fs}	19	24	29	mS	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}, V_{G2S} = 4 \text{ V}$	
						$R_G = 47 \text{ k}\Omega, f = 1 \text{ kHz}$	
Input capacitance	Ciss	1.4	1.7	2.0	pF	$V_{DS} = 5 \text{ V}, V_{G1} = 5 \text{ V}$	
Output capacitance	Coss	0.7	1.1	1.5	pF	$V_{G2S} = 4 \text{ V}, R_G = 47 \text{ k}\Omega$	
Reverse transfer capacitance	Crss	_	0.019	0.04	pF	f = 1 MHz	
Power gain	PG	17	21.5	_	dB	V _{DS} = 5 V, V _{G1} = 5 V	
Noise figure	NF	_	1.85	2.4	dB	$V_{G2S} = 4 \text{ V}, R_G = 47 \text{ k}\Omega$	
						f = 900 MHz	

Main Characteristics

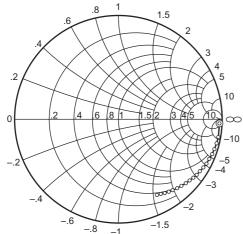








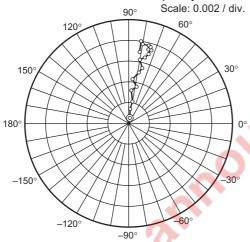
S11 Parameter vs. Frequency



Test Condition: V_{DS} = 5 V , V_{G1} = 5 V V_{G2S} = 4 V , R_G = 47 k Ω , Zo = 50 Ω

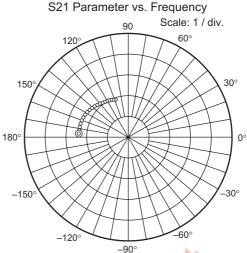
50 to 1000 MHz (50 MHz step)

S12 Parameter vs. Frequency



Test Condition: $V_{DS} = 5 \text{ V}$, $V_{G1} = 5 \text{ V}$ $V_{G2S} = 4 \text{ V}, R_G = 47 \text{ k}\Omega$ $Z_0 = 50\Omega$

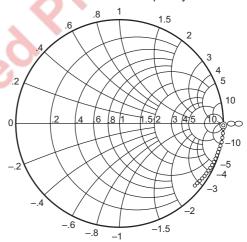
> 50 to 1000 MHz (50 MHz step) **—**



Test Condition: $V_{DS} = 5 \text{ V}$, $V_{G1} = 5 \text{ V}$ $V_{G2S} = 4 \text{ V}$, $R_{G} = 47 \text{ k}\Omega$, $Z_0 = 50\Omega$

50 to 1000 MHz (50 MHz step)

S22 Parameter vs. Frequency



Test Condition: V_{DS} = 5 V , V_{G1} = 5 V $V_{G2S} = 4 \ V \ , R_G = 47 \ k\Omega \ ,$ Zo = 50Ω

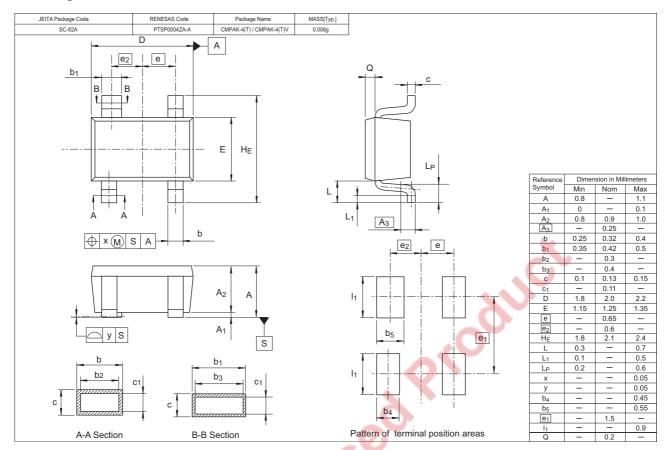
50 to 1000 MHz (50 MHz step)

S Parameter

 $(V_{DS}=V_{G1}=5V,\,V_{G2S}=4V,\,R_G=47k\Omega,\,Zo=50\Omega)$

f(MHz)	S11		S21		S12		S22	
1(1VII 12)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.
50	0.974	-2.8	2.40	176.4	0.00057	78.1	0.997	-2.0
100	0.974	-10.0	2.38	172.2	0.00144	82.4	0.998	-4.2
150	0.974	-13.6	2.38	168.4	0.00211	78.7	0.997	-6.0
200	0.965	-16.5	2.37	164.1	0.00316	84.8	0.995	-8.1
250	0.963	-20.0	2.35	160.4	0.00358	76.3	0.994	-10.2
300	0.953	-23.7	2.32	156.8	0.00431	84.0	0.992	-12.2
350	0.947	-26.8	2.30	152.9	0.00503	79.0	0.990	-14.2
400	0.942	-29.6	2.28	148.6	0.00545	76.6	0.987	-16.2
450	0.929	-32.8	2.26	144.9	0.00630	80.3	0.984	-18.1
500	0.923	-35.4	2.21	141.2	0.00646	76.1	0.981	-20.2
550	0.912	-38.5	2.19	137.6	0.00693	73.7	0.977	-22.1
600	0.903	-41.2	2.15	134.2	0.00732	72.9	0.974	-24.1
650	0.886	-44.2	2.12	130.6	0.00729	74.6	0.971	-26.0
700	0.879	-46.8	2.08	127.4	0.00733	72.0	0.967	-27.8
750	0.873	-49.2	2.06	124.3	0.00762	74.5	0.962	-29.7
800	0.859	-52.4	2.03	120.8	0.00756	73.7	0.959	-31.7
850	0.846	-55.4	2.00	117.3	0.00772	75.5	0.955	-33.6
900	0.836	-58.0	1.96	114.3	0.00775	79.6	0.951	-35.5
950	0.827	-60.4	1.93	111.0	0.00801	81.7	0.946	-37.3
1000	0.815	-62.8	1.89	108.0	0.00704	81.0	0.942	-39.4

Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
BB501CAS-TL-E	3000	φ 178 mm Reel, 8 mm Emboss Taping

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